DEFENSE LOGISTICS
AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

August 7, 2026

Christopher Jones
Senior Quality Manager
International Rectifier HiRel Products, Inc.
An Infineon Technologies Company
205 Crawford Street
Leominster, MA 01453

Dear Mr. Jones:

Re: Full Certification Class Q/B and V/S with Radiation Hardness for MIL-PRF-38535; FSC 5962; VQC-26-040476; Wilkinson. CN: 095947.

International Rectifier HiRel Products, Inc. has demonstrated to DLA Weapons Support that it complies with MIL-PRF-38535 for Class Q and Class V products. MIL-PRF-38535 is the performance specification used by the Department of Defense for monolithic integrated circuits that operate in severe environments.

This letter supersedes the previous Class Q/V Certification letter issued by DLA Land and Maritime (VQC-25-393396) granted to Infineon Technologies to reflect the current certification status of your facilities as documented on the QM Plan, HBP-QM Plan for QML Microcircuits (03). This letter (VQC-26-040476) is effective immediately.

In addition, the parts that are manufactured using the certified technology flows are being listed on the QML-38535. This will allow International Rectifier HiRel Products, Inc. to mark parts with "Q" or "QML". These designators have been authorized by the Department of Defense for parts that have been produced to a QML specification, (i.e., one which allows less government oversight), the use of world-wide commercial production lines, reduced finished product testing based on statistical process controls (SPC), and other cost advantages.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter VQC-26-040475, or at facilities approved by the International Rectifier HiRel Products, Inc. Technical Review Board using its MIL-PRF-38535 Quality Management Program Plan.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program and SD-6.

Any and all of the facilities mentioned in the enclosure are subject to an audit by the Qualifying Activity, at any time. Offshore facilities are subject to all conditions of MIL-PRF-38535. The QML manufacturer is responsible for arranging for the qualifying activity to gain access to all applicable manufacturing facilities to perform site assessments to MIL-PRF-38535 requirements.

QPL/QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products. Failure to provide prior notification may be grounds for removal from QML-38535.

Finally, it is required that the following activities be reported promptly to DLA Weapons Support:

1. Changes to certified facilities, designs, process flows, or approved testing subcontractors
2. Problem evaluation and a corrective action when:
   a. A Technology Conformance Inspection (TCI) or Qualification Conformance Inspection (QCI) failure has been validated
   b. The reliability of shipped parts is questionable
3. Test optimization, including:
   a. Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
   b. Changing, suspending or canceling a prior test optimization
4. Additions or deletions of parts in the QML-38535
5. Change of company QML contact, TRB Chairperson or other key QML personnel
6. Change of company name and/or location

This certification is valid until terminated by written notice from the qualifying activity. If warranted, it may be withdrawn by this Agency at any time.

If you have any questions, please contact Mr. Patrick Wilkinson at 614-693-3099.

Sincerely,

ADAMS.MICHAEL.S.1230230427

Digitally signed by ADAMS.MICHAEL.S.1230230427
Date: 2026.08.11 07:35:39 -04'00'

MICHAEL S. ADAMS
Chief
Custom Devices Branch

Enclosure

OPERATION	FACILITY	LOCATION	TECHNOLOGY	FLOW NUMBER
Design & Mask Design	Infineon Technologies	Andover, MA	CMOS	HBP-36
Mask (Photomasks)	Tekscend	Round Rock, TX	CMOS	HBP-36
Wafer Fab	Infineon Technologies	Dresden, Germany	200 mm (8 in) wafer 130 nm CMOS	C1HR9001
	Infineon Technologies	Regensburg, Germany	Backside grind and metal (TiNiVAg)	C11HVHIREL
Wafer Probe	Infineon Technologies	Leominster, MA	Teradyne Eagle Test System	D06
Dicing, Pick & Place	Infineon Technologies	Leominster, MA	Dicing, pick & place	D06
	Micross	Apopka, FL	Dicing, pick & place	D06
Assembly	Infineon Technologies	Leominster, MA	Class Q, V assembly	DCA
	Tintronics	Huntsville, AL	Hot solder dip	DCS
	Micross	Manchester, NH	Hot solder dip	DCS
Environmental, Screening & Electrical Test	Infineon Technologies	Leominster, MA	Class Q, V test	DCS
Marking (Top & Bottom)	Infineon Technologies	Leominster, MA	Laser marking	DCS
Radiation Assurance (Appendix C) Group E	Reference laboratory suitability letter VQC-26-040475			